

650V N-CHANNEL ENHANCEMENT MODE MOSFET

MAIN CHARACTERISTICS

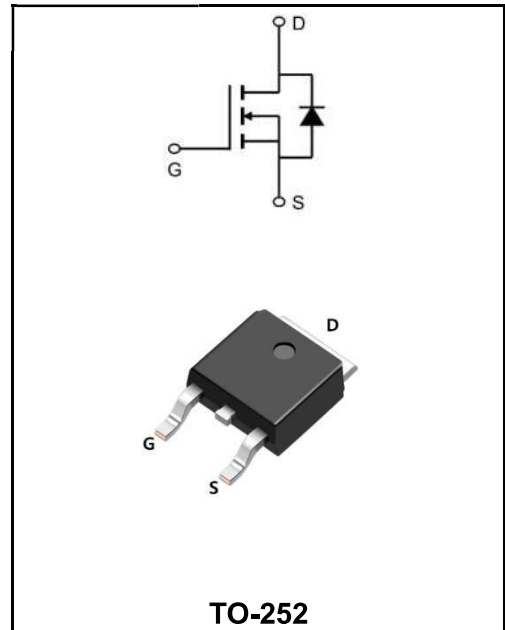
I_D	10A
V_{DSS}	650V (Type:720V)
R_{DS(on)-typ(@V_{GS}=10V)}	< 950mΩ (Type:860mΩ)

Features

◆ Is CoolFET II MOSFET

Application

- ◆ Uninterruptible Power Supply(UPS)
- ◆ Power Factor Correction (PFC)



Product Specification Classification

Part Number	Package	Marking	Pack
YFWJ10N65AD	TO-252	YFW J10N65AD XXXXX	2500PCS/Tape

Maximum Ratings at Tc=25°C unless otherwise specified

Characteristics	Symbols	Value	Units
Drain-Source Voltage (V _{GS} = 0V)	V_{DS}	650	V
Continuous Drain Current	I_D	10	A
Pulsed Drain Current(note1)	I_{DM}	30	A
Gate - Source Voltage	V_{GS}	±30	V
Single Pulse Avalanche Energy(note2)	E_{AS}	125	mJ
Power Dissipation(T _A =25°C)	P_D	25.5	W
Operating Junction and Storage Temperature Range	T_J , T_{STG}	-55 to +150	°C
Thermal Resistance, Junction-to-case	R_{θJC}	4.9	°C/W
Thermal Resistance, Junction ambient	R_{θJA}	49	°C/W

Maximum Ratings at Tc=25°C unless otherwise specified

Characteristics	Test Condition	Symbols	Min	Typ	Max	Units
Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	BV_{DSS}	650	720	-	V
Breakdown voltage temperature coefficient	Reference to 25°C, $I_D=250\mu A$	$\Delta BV_{DSS}/\Delta T_J$	-	0.7	-	V/°C
Drain -Source Leakage Current	$V_{DS}=650V, V_{GS}=0V$	I_{DSS}	-	-	1	μA
	$V_{DS}=520V, T_C=125^\circ C$		-	-	50	
Gate to source leakage current, forward	$V_{GS}=30V, V_{DS}=0V$	I_{GSS}	-	-	100	nA
Gate to source leakage current, reverse	$V_{GS}=-30V, V_{DS}=0V$		-	-	-100	
Gate- Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	$V_{GS(th)}$	2.5	3.3	4.5	V
Drain to source on state resistance	$V_{GS}=10V, I_D=3.2A$	$R_{DS(ON)}$	-	860	950	mΩ
Input Capacitance	$V_{DS}=100V$ $V_{GS}=0V$ $f=1MHz$	C_{iss}	-	263	-	pF
Output Capacitance		C_{oss}	-	13.7	-	
Reverse Transfer Capacitance		C_{rss}	-	1.06	-	
Turn-on delay time	$V_{DS}=400V$ $I_D=2.2A$ $R_G=4.7\Omega$ $V_{GS}=10V$	$t_{d(on)}$	-	12.8	-	nS
Rising time		T_r	-	26.4	-	
Turn-Off Delay Time		$t_{d(OFF)}$	-	22.2	-	
Fall Time		t_f	-	75.6	-	
Total Gate Charge	$V_{DS}=480V$ $I_D=2A$ $V_{GS}=10V$	Q_g	-	1.07	-	nC
Gate-Source Charge		Q_{gs}	-	3.63	-	
Gate-Drain Charge		Q_{gd}	-	7.72	-	
Continuous source current	Integral reverse p-n Junction diode in the MOSFET	I_S	-	-	5	A
Pulsed source curren		I_{SM}	-	-	15	
Diode forward voltage drop.	$I_S = 3.2A, V_{GS} = 0V$	V_{SD}	-	0.7	1.5	V
Reverse Recovery Time	$V_{GS} = 0V, I_S = 3.2A, V_{DS}=400V$ $diF/dt = 100A /\mu s$	t_{rr}	-	313	-	nS
Reverse Recovery Charge		Q_{rr}	-	0.92	-	uC

Note :

- 1、 The data tested by surface mounted on a 1 inch2 FR-4 board with 2OZ copper.
- 2、 The EAS data shows Max. rating . L=0.5mH, IAS =2.3A, VDD =50V, RG=25Ω
- 3、 The test condition is Pulse Test: $ISD \leq ID$, $di/dt = 100A/us$, $VDD \leq BVDSS$, Starting at $T_J = 25^\circ C$
- 4、 The power dissipation is limited by 150°C junction temperature
- 5、 The data is theoretically the same as ID and IDM , in real applications , should be limited by total power dissipation.

Ratings and Characteristic Curves

Typical Characteristics

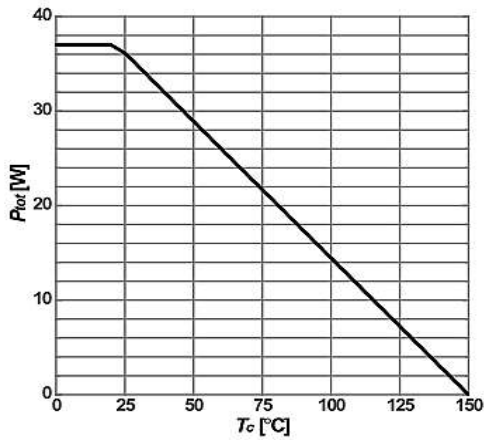


Figure1: Power dissipation (Non FullPAK)

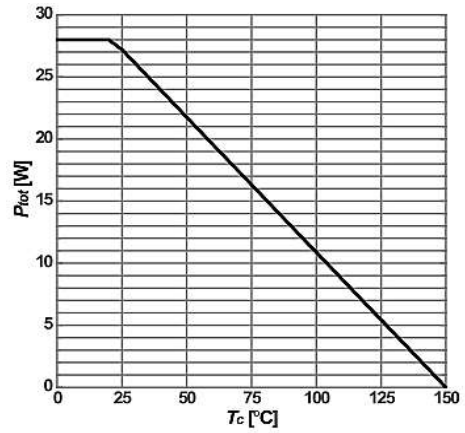


Figure2: Power dissipation (FullPAK)

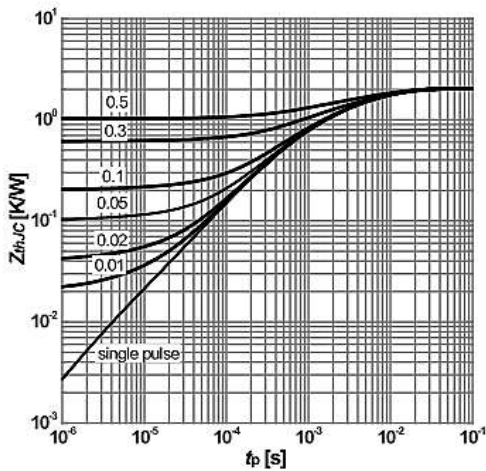


Figure3:Max. transient thermal impedance
 $Z_{thJC}=f(t_p)$; parameter: $D= t_p/T$

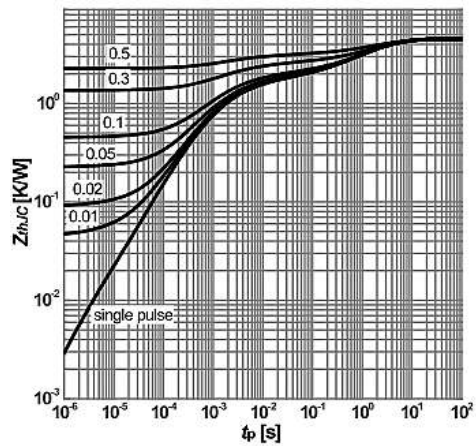


Figure4:Max. transient thermal impedance
 $Z_{thJC}=f(t_p)$; parameter: $D= t_p/T$

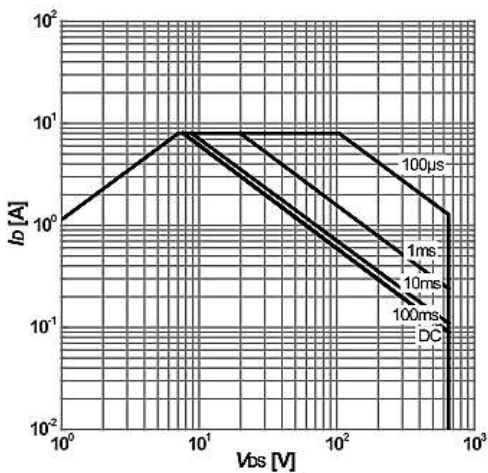


Figure5: Safe operating area (Non FullPAK)
 $I_b=f(V_{bs})$; $T_j=25^\circ\text{C}$; $D=0$; parameter: t_p

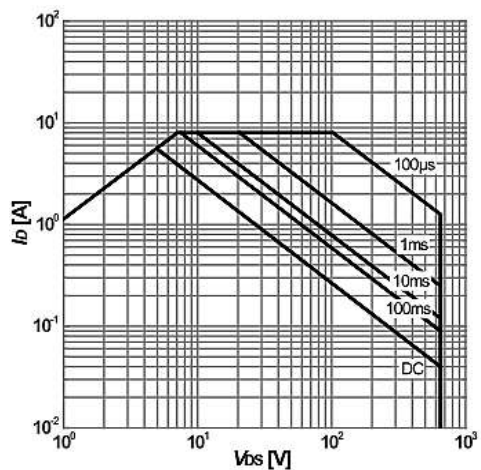


Figure6: Safe operating area (FullPAK)
 $I_b=f(V_{bs})$; $T_j=25^\circ\text{C}$; $D=0$; parameter: t_p

Ratings and Characteristic Curves

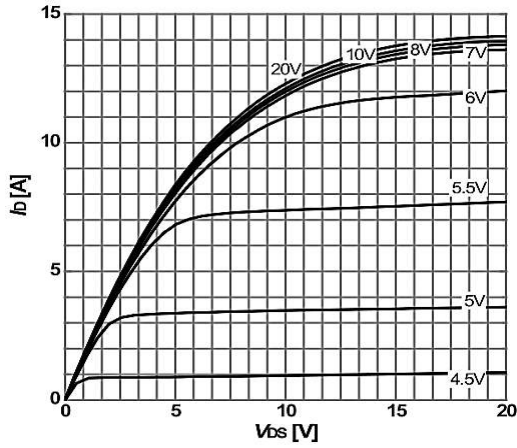


Figure 7: Typ. output characteristics

$I_D=f(V_{DS}); T_J=25^{\circ}\text{C};$ parameter: V_{GS}

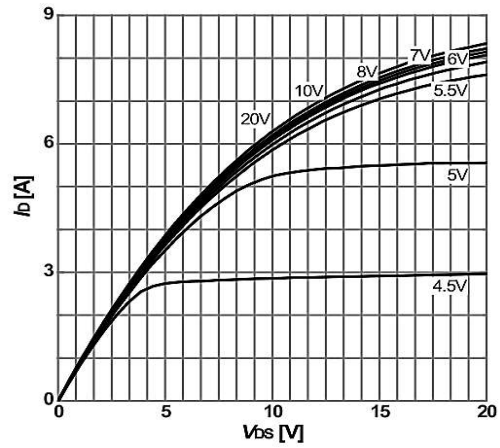


Figure 8: Typ. output characteristics

$I_D=f(V_{DS}); T_J=125^{\circ}\text{C};$ parameter: V_{GS}

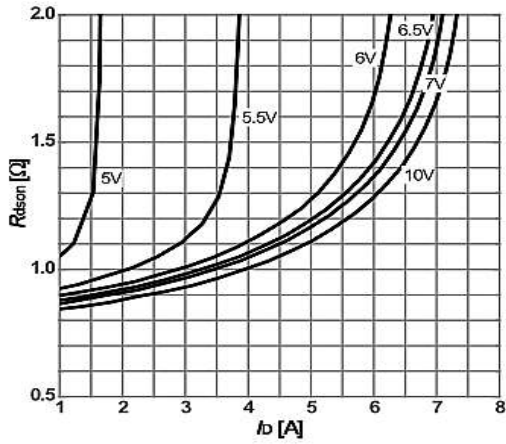


Figure 9: Typ. drain-source on-state resistance

$R_{DS(on)}=f(I_D); T_J=25^{\circ}\text{C};$ parameter: V_{GS}

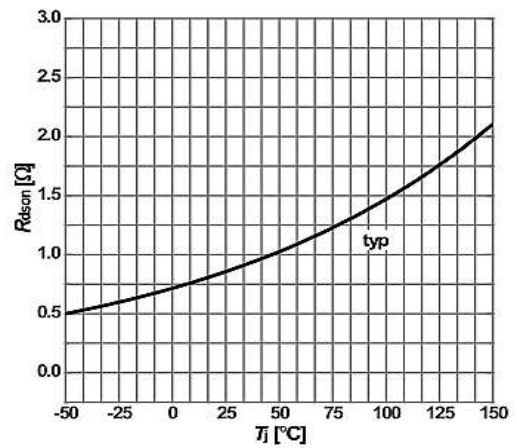


Figure 10: drain-source on-state resistance

$R_{DS(on)}=f(T_J); I_D=3.2\text{A}; V_{GS}=10\text{V}$

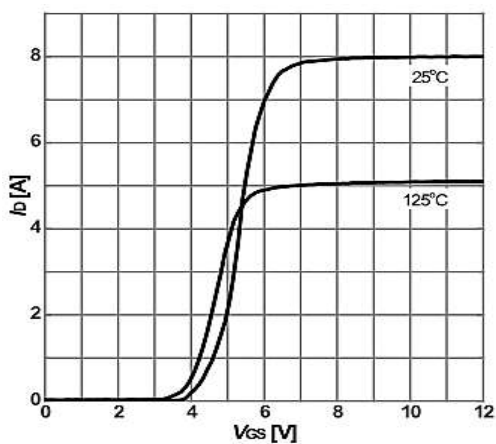


Figure 11: Type. transfer characteristics

$I_D=f(V_{GS}); V_{DS}=20\text{V};$ parameter: T_J

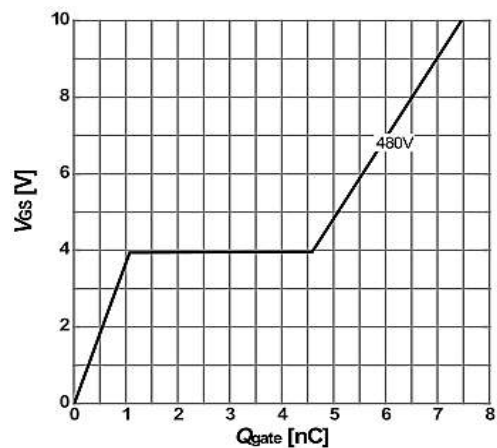


Figure 12: Type. gate charge

$V_{GS}=f(Q_{gate}); I_D=3.2\text{A pulsed}; V_{DS}=480\text{V}$

Package Outline Dimensions Millimeters

TO-252

Dim.	Min.	Typ.	Max.
A	2.10	-	2.50
A2	0	-	0.10
B	0.66	-	0.86
B2	5.18	-	5.48
C	0.40	-	0.60
C2	0.44	-	0.58
D	5.90	-	6.30
D1	5.30REF		
E	6.40	-	6.80
E1	4.63	-	-
G	4.47	-	4.67
H	9.50	-	10.70
L	1.09	-	1.21
L2	1.35	-	1.65
V1	-	7°	-
V2	0°	-	6°
All Dimensions in millimeter			